

CLAIMS

What is claimed and desired to be secured by Letters Patent is as follows:

1. A method of reducing electromagnetic emissions from an electronic circuit, said electronic circuit comprising at least one electrical component and at least one grounding point, said method comprising:
applying a non-conductive coating over said electrical component; and
applying a conductive coating over said non-conductive coating and in contact with said grounding point so as to ground said conductive coating and thereby reduce electromagnetic emissions from said electronic circuit.
2. The method of claim 1, wherein a hole is formed in said non-conductive coating above said grounding point so as to enable contact between said conductive coating and said grounding point.
3. The method of claim 1, wherein said grounding point is located proximate an edge of said electronic circuit, and wherein said non-conductive coating does not coat said edge of said electronic circuit so as to enable contact between said conductive coating and said grounding point.
4. The method of claim 1, wherein said non-conductive coating conforms to said electrical component, and wherein said conductive coating conforms to said non-conductive coating and said grounding point.
5. An electronic circuit comprising at least one electrical component and at least one grounding point, wherein a non-conductive coating is applied over said electrical component, and wherein a conductive coating is applied over said non-conductive coating and in contact with said grounding point so as to ground said conductive coating.
6. The electronic circuit of claim 5, wherein a hole is formed in said non-conductive coating above said grounding point so as to enable contact between said conductive coating and said grounding point.

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7. The electronic circuit of claim 5, wherein said grounding point is located proximate an edge of said electronic circuit, and wherein said non-conductive coating does not coat said edge of said electronic circuit so as to enable contact between said conductive coating and said grounding point.

8. The electronic circuit of claim 5, wherein said non-conductive coating conforms to said electrical component, and wherein said conductive coating conforms to said non-conductive coating and said grounding point.

9. The electronic circuit of claim 5, wherein said non-conductive coating comprises a conformal coating material selected from the following group: insulating tape, rubber, silicone, room-temperature vulcanizing silicone rubber, plastic, insulating varnish, and combinations thereof.

10. The electronic circuit of claim 5, wherein said conductive coating comprises a conformal coating material selected from the following group: conductive tape, conductive paint, silver paint, and combinations thereof.

11. The electronic circuit of claim 5, wherein said non-conductive coating is applied over a plurality of electrical components of said electronic circuit.